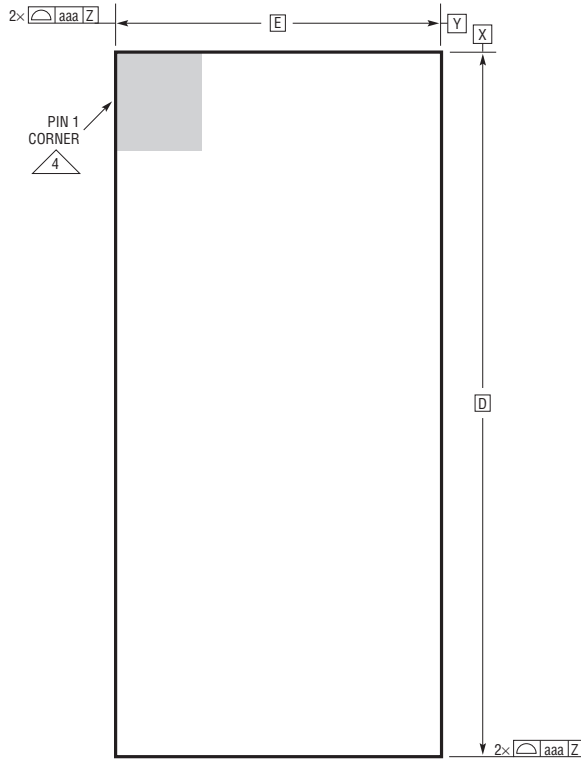
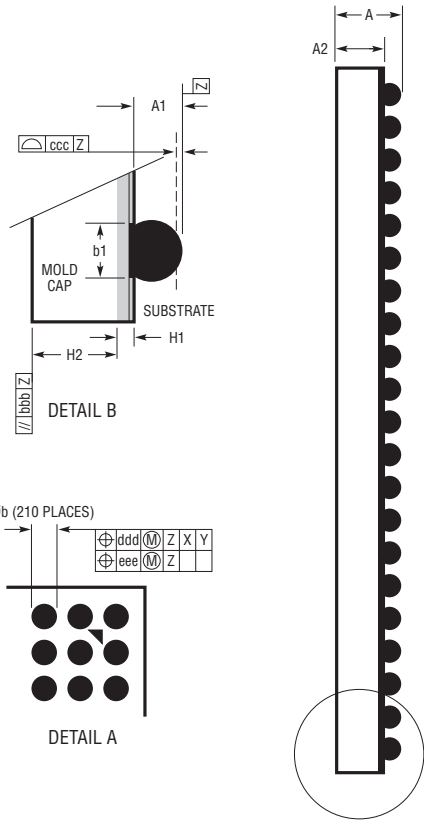


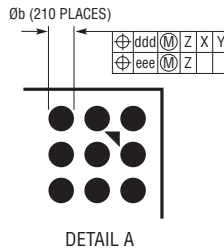
BGA Package
210-Lead (16.9mm × 8.1mm × 1.52mm)
 (Reference LTC DWG# 05-08-1828 Rev B)



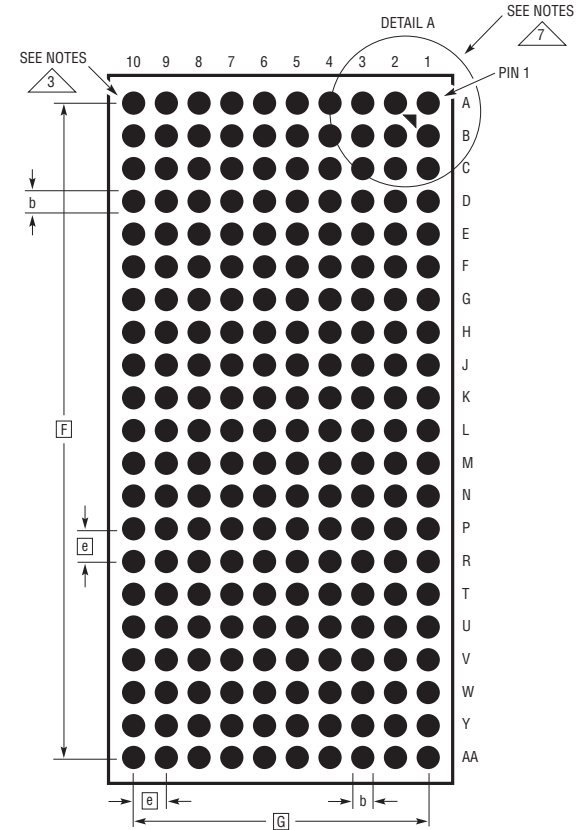
PACKAGE TOP VIEW



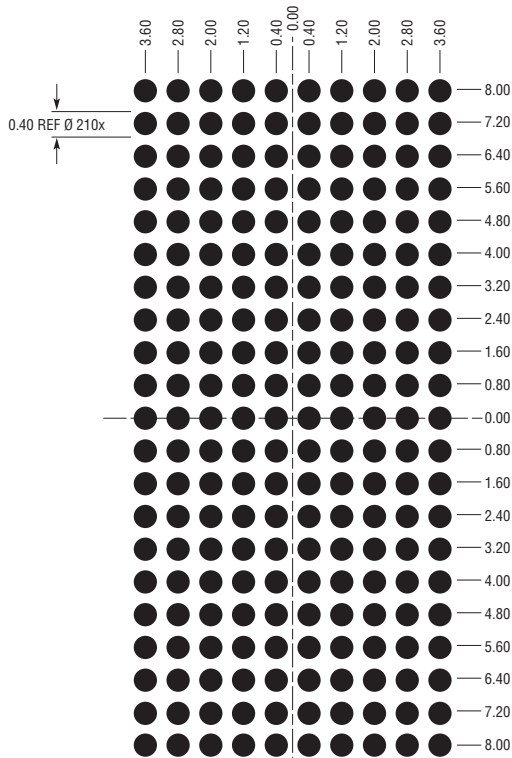
DETAIL B
 PACKAGE SIDE VIEW



DETAIL A



PACKAGE BOTTOM VIEW



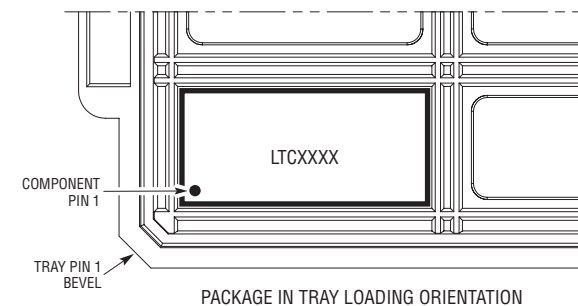
SUGGESTED PCB LAYOUT
 TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	1.32	1.52	1.72	
A1	0.30	0.40	0.50	BALL HT
A2	1.02	1.12	1.22	
b	0.35	0.50	0.65	BALL DIMENSION
b1	0.37	0.40	0.43	PAD DIMENSION
D		16.90		
E		8.10		
e		0.80		
F		16.00		
G		7.20		
H1		0.32 REF		SUBSTRATE THK
H2		0.80 REF		MOLD CAP HT
aaa			0.15	
bbb			0.20	
ccc			0.20	
ddd			0.15	
eee			0.08	

TOTAL NUMBER OF BALLS: 210

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. BALL DESIGNATION PER JEP95
4. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION